

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TONGBI JIANG

Serial No.:

EXAMINER:

Filing Date: 10/15/2003

Division of Serial No. 10/178,703
filed 06/24/2002

Art Unit:

For: No Flow Underfill Material And Method
For Underfilling Semiconductor Components

Attorney Docket No. 01-0219.1

**PRELIMINARY AMENDMENT
SUBMITTED WITH CONTINUING APPLICATION
UNDER 37 CFR 1.53(b)**

OCTOBER 15, 2003

Mail Stop Patent Application
Commissioner of Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This Preliminary Amendment is being filed with a divisional application under 37 CFR 1.53(b). Please amend the captioned case as follows.